



# CHALLENGES AHEAD IN AUTOMOTIVE ELECTRONICS

**Dr. Jean-Luc di Paola-Galloni**

Corporate VP Valeo -

President Inside IA

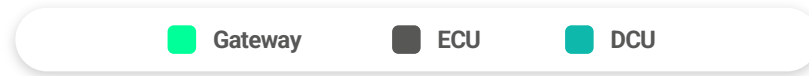
Chair of the Private members board of ECSEL



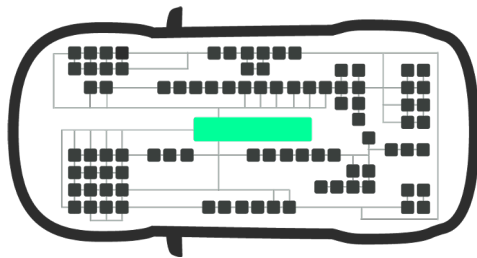
**VIRTUAL Conference**

17-19 November 2021

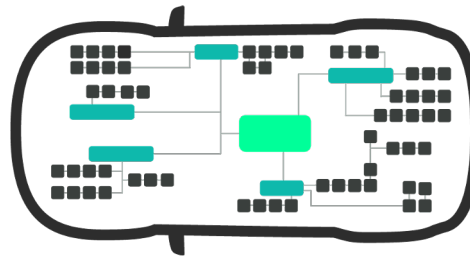
# ELECTRIC AND ELECTRONICS ARCHITECTURE IS EVOLVING FROM INDEPENDENT, FUNCTION-SPECIFIC ECUs TOWARDS A CENTRALIZED ARCHITECTURE



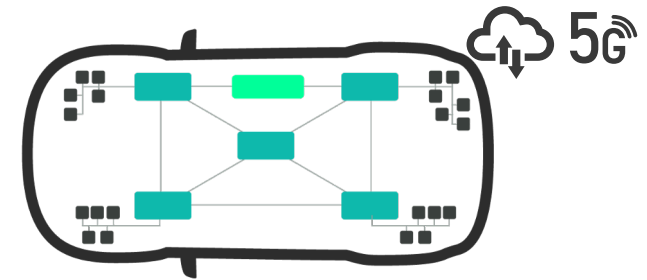
**TODAY**  
Distributed



**TOMORROW**  
Domain Centralization



**FUTURE**  
Vehicle Centralized / Virtual Domain



*Distinctive hardware platforms, limited HW abstraction*

*Single software platform, full hardware abstraction*

## TECHNOLOGY

- 80-100 ECUs
- Multiple CAN, LIN, Ethernet, Flexray, MOST communication links

- 4-5 high-performance DCUs
- Multiple sensor/actuator ECUs
- 1 CAN bus per zone
- 1 Ethernet backbone

- Cluster of high-performance computers
- Multiple sensors/actuator ECUs
- 1 CAN bus per zone
- 1 Ethernet backbone

## CHARACTERISTICS

- Distributed control
- Many nodes
- Inter-communication via central gateway

- Dedicated domains
- Consolidation of functions in DCUs
- Routing between DCUs handled by advanced gateway

- Virtualized functions executed in high performance computers
- Zone-dependent sensors/actuator ECUs (domain-independent, scalable)
- Routing complexity handled by advanced gateway

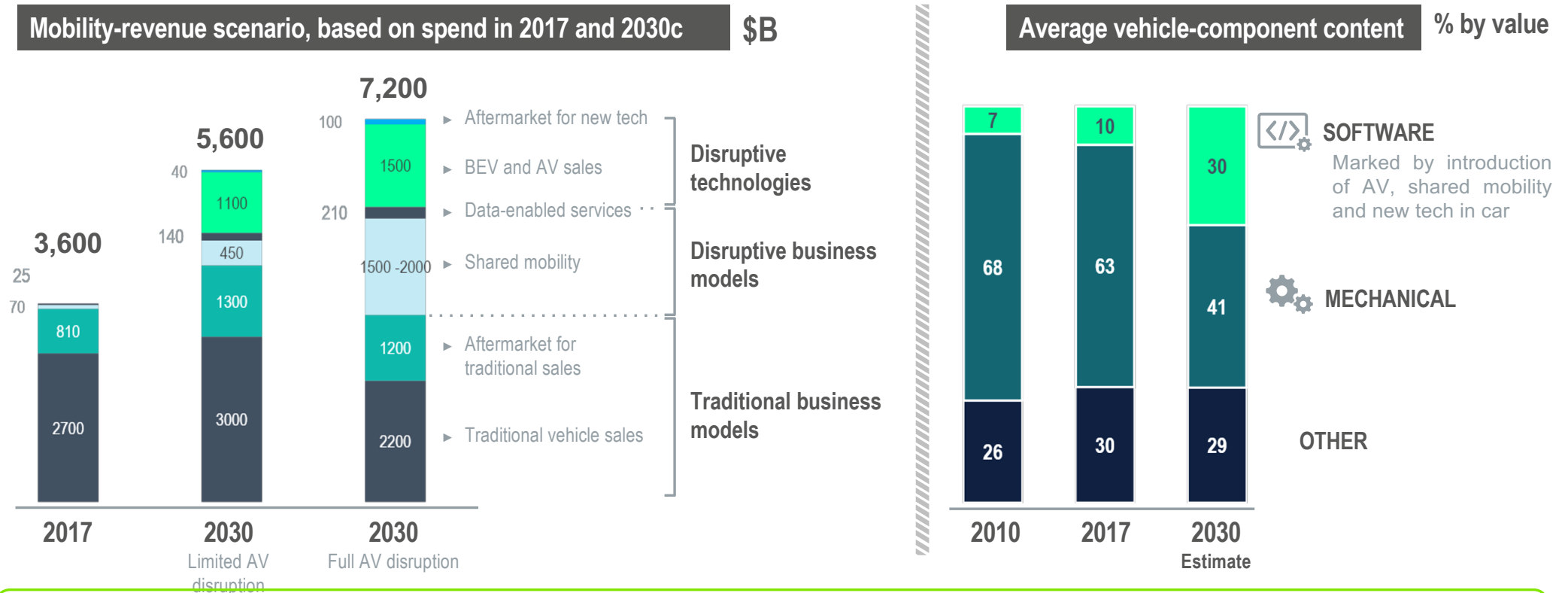
Source: Roland Berger - Computer on Wheels - January 2020 & Valeo analysis

# AUTOMOTIVE CONTROL CHIPS EVOLVE FROM SIMPLE MICROCONTROLLER UNITS TO ADVANCED ARTIFICIAL INTELLIGENCE ENGINES

	AUTOMOTIVE MCU	AUTOMOTIVE MCU	AI ENGINE
	<b>16 bit</b> <b>Legacy Product</b> (e.g. ST Micro ST10)	<b>32 bit</b> <b>Next Gen MCU</b> (e.g. Infineon Aurix)	<b>64 bit</b> <b>AI Engine</b> (e.g. Tesla FSD chip)
CHIP DESIGN	<ul style="list-style-type: none"> <li>• Single core</li> </ul>	<ul style="list-style-type: none"> <li>• Up to six Tricore CPUs</li> </ul>	<ul style="list-style-type: none"> <li>• 12 CPUS + 2GPU + 2NPU</li> </ul>
CHIP SIZE	<ul style="list-style-type: none"> <li>• 180nm manufacturing node</li> </ul>	<ul style="list-style-type: none"> <li>• 65 and 90nm</li> </ul>	<ul style="list-style-type: none"> <li>• 14nm</li> </ul>
PINS	<ul style="list-style-type: none"> <li>• 144 pin package</li> </ul>	<ul style="list-style-type: none"> <li>• 80-516 pins</li> </ul>	<ul style="list-style-type: none"> <li>• 2,116 pins</li> </ul>
CHIP COST	<ul style="list-style-type: none"> <li>• &lt;10 USD typical</li> </ul>	<ul style="list-style-type: none"> <li>• 10s of USD</li> </ul>	<ul style="list-style-type: none"> <li>• 100s to 1000s of USD</li> </ul>
APPLICATIONS	<ul style="list-style-type: none"> <li>• Monolithic – single task applications</li> </ul>	<ul style="list-style-type: none"> <li>• Wide application range: e.g. domain control, chassis, safety, engine, ADAS</li> </ul>	<ul style="list-style-type: none"> <li>• L4/L5 autonomous driving</li> </ul>
<b>INCREASING RANGE OF APPLICATIONS, COMPLEXITY OF ARCHITECTURE, MANUFACTURING AND COST</b>			
	1990s	2000s	2019

Source: Roland Berger - Computer on Wheels - January 2020

# THERE IS VALUE IN THERE: NEW PROFIT POOLS ARE ON-GOING



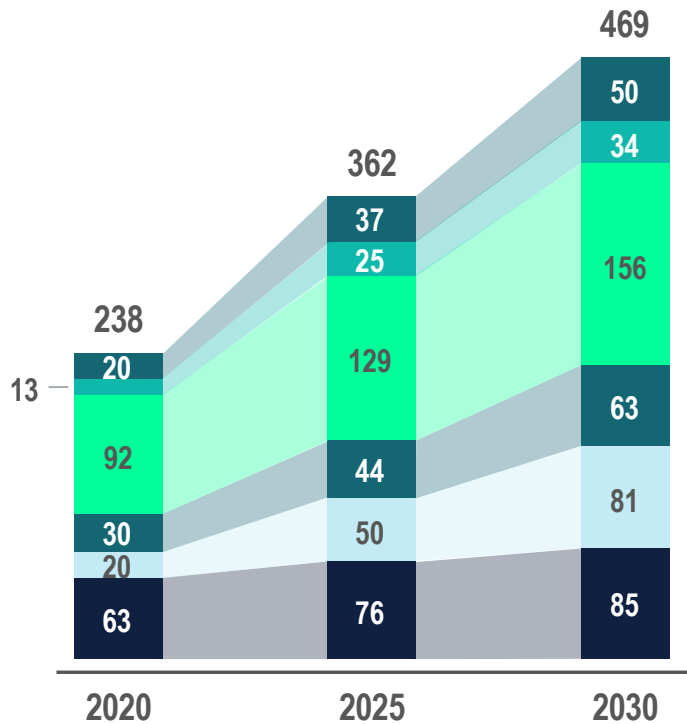
**Electric and autonomous vehicles will unlock new potential as revenues fragment from traditional streams and software content increases**

Source: Mckinsey - How sharing the road is likely to transform American mobility - April 2019

# AUTOMOTIVE HW/SW MARKET IS EXPECTED TO GROW (ANNUAL CAGR OF 7% UNTIL 2030), DRIVEN BY POWER ELECTRONICS, SW, AND ECUS/DCUS

## AUTOMOTIVE SW and E/E MARKET

\$ billions



Components	CAGR 2020-30
▶ SW (functions, OS, middleware)	+9%
▶ Integration, verification & validation services	+10%
▶ ECUs/DCUs	+5%
▶ Sensors	+8%
▶ Power electronics (excl. Battery cells)	+15%
▶ Other electronic components (harnesses, controls, switches, displays)	+3%
<b>TOTAL</b>	<b>+7%</b>

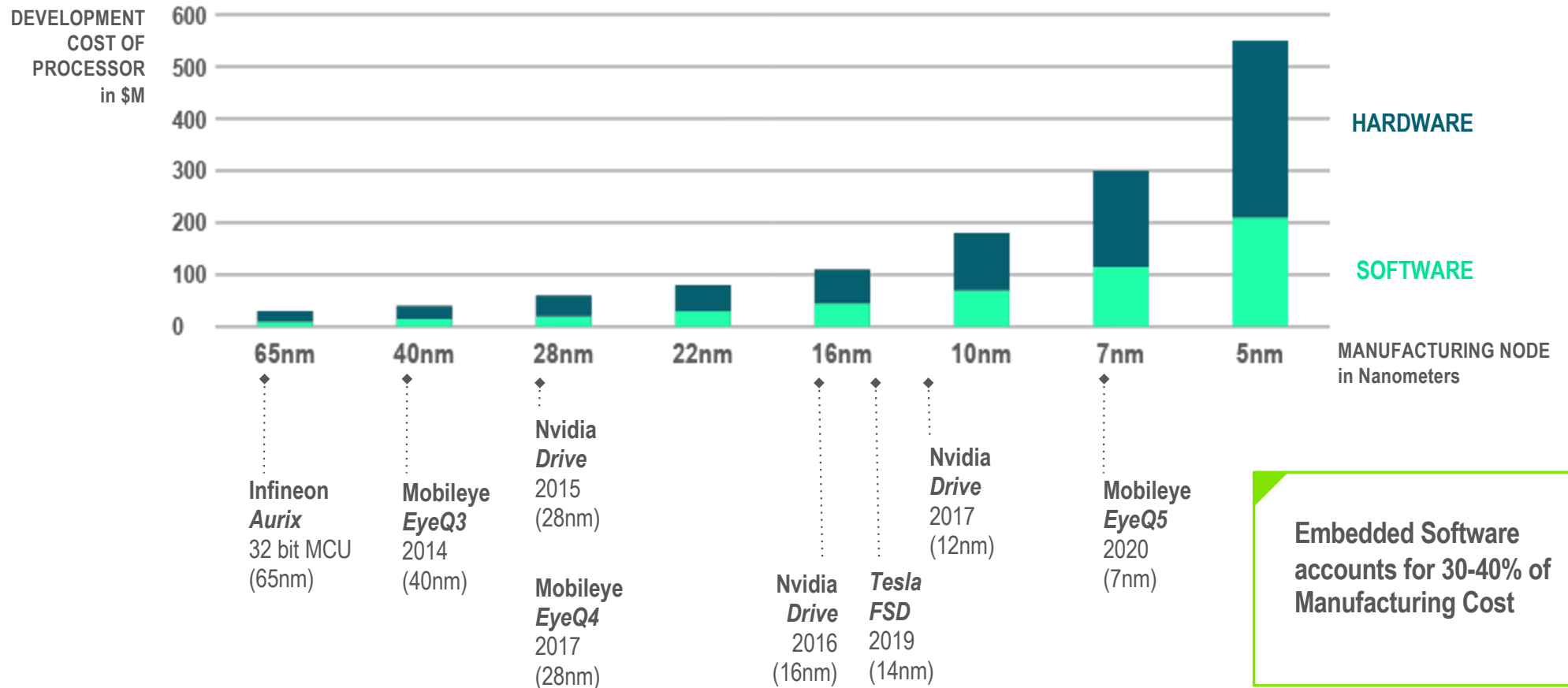
## Total electronics & SW by geography in 2030

	EU	112
	China	161
	US	
	Canada	68
	Mexico	
	Korea	
	Japan	50
	RoW	78
<b>TOTAL</b>		<b>469</b>

Automotive sales		\$ billions	
2020	2025	2020	2030
2,755	3,027	2,755	3,800
<b>CAGR 2020-30</b>		<b>+3%</b>	

Source: Mckinsey - Automotive Software and Electronics 2030 - July 2019

# AT THE SAME TIME, PROCESSOR COSTS ARE INCREASING

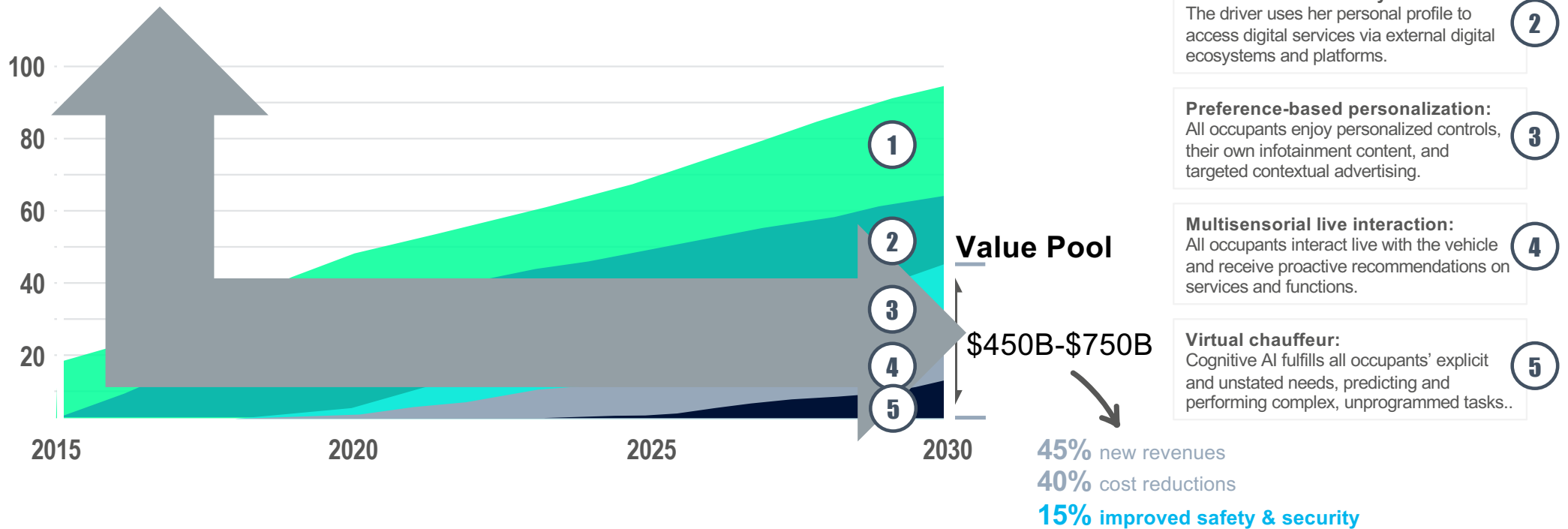


Source: Roland Berger - Automotive disruption radar 7

# CONNECTIVITY IS ALSO BRINGING NEW CHALLENGES & COST ALLOCATIONS

## GLOBAL PENETRATION OF CONNECTED CARS

% of new light-vehicle sales by connectivity level



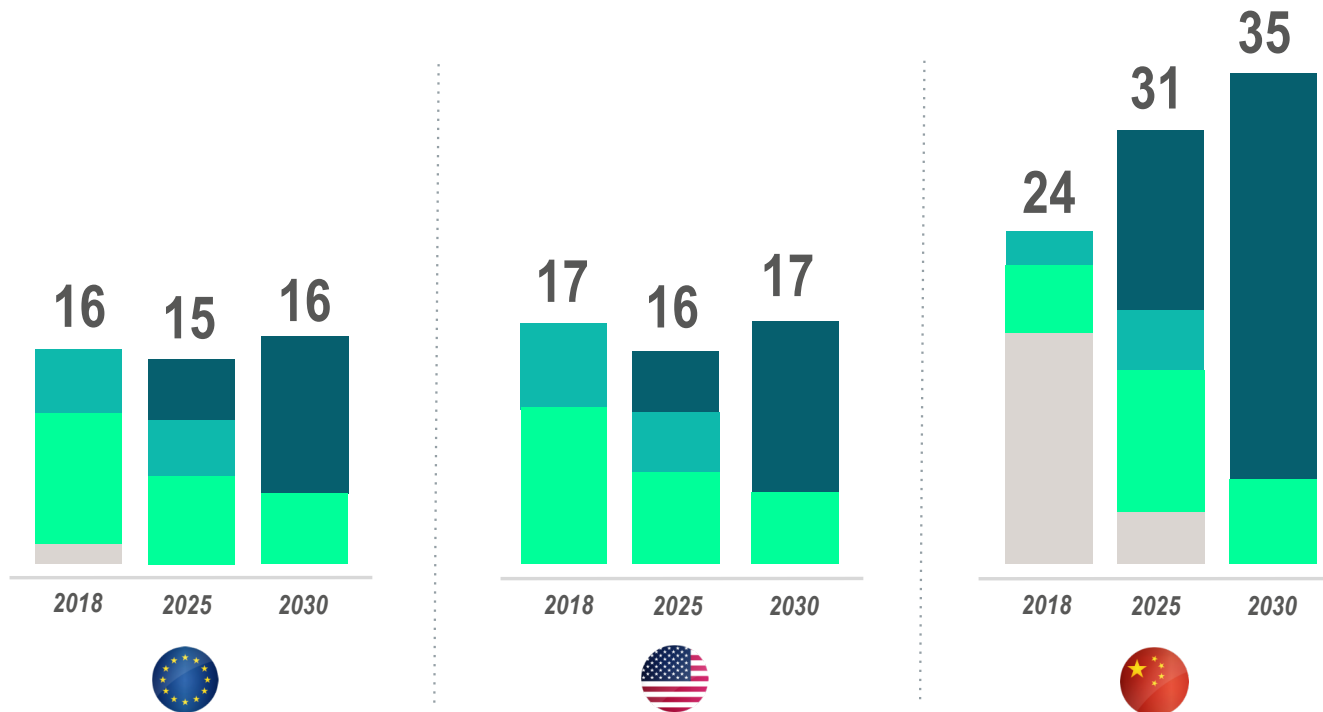
# TECHNOLOGY IS EXPECTED TO SHIFT FROM 3G/4G TOWARDS 5G READINESS

## MARKET OUTLOOK OF CONNECTED VEHICLES IN TOTAL NEW VEHICLE SALES BY 2030

M units

pwc

0G 2G/3G 4G 5G



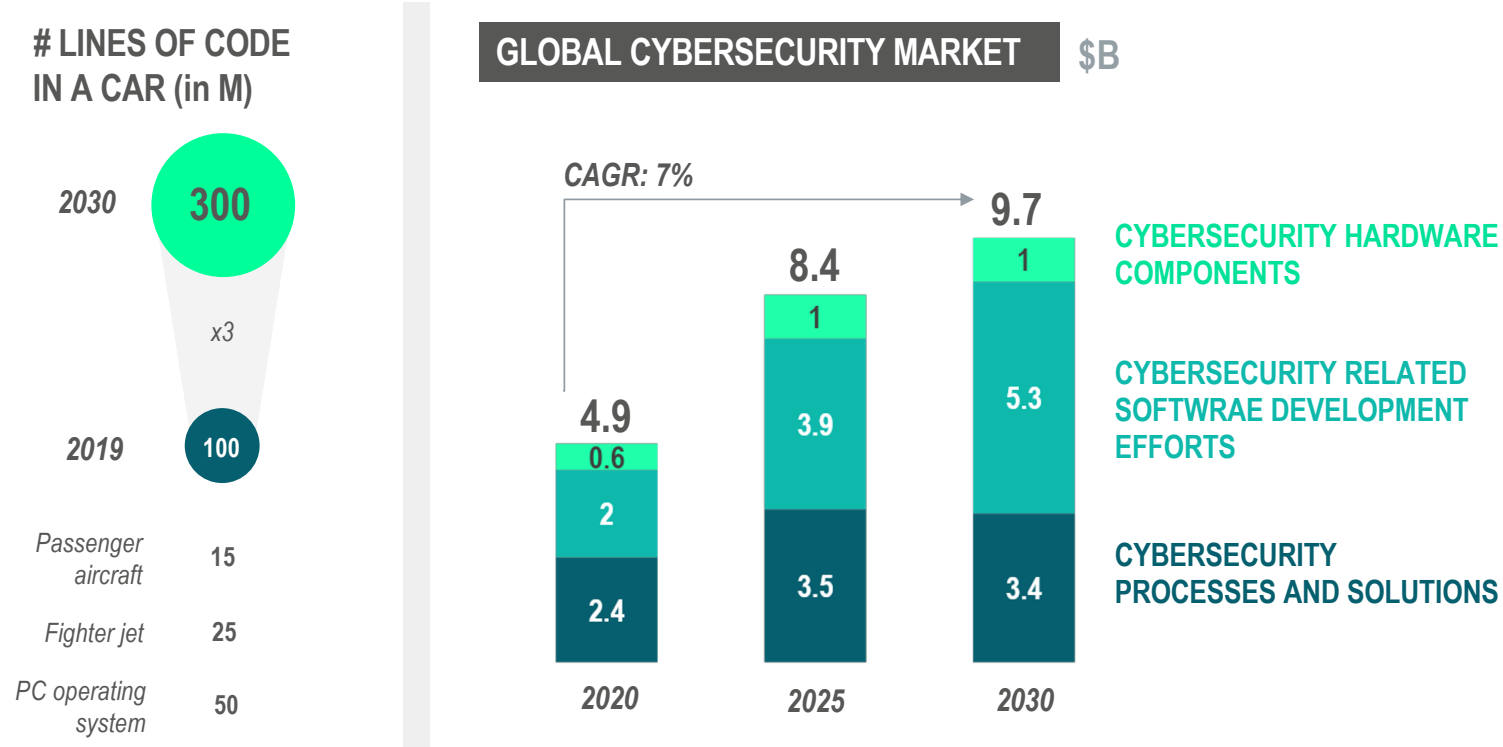
Around 70% of new cars will be 5G connected by 2030 ; 4G will only be a temporary solution

5G will be key enabler for new connected services and shift towards cloud-based vehicle architecture

Source: PWC - Digital Auto Report - 2019



# GROWING SOFTWARE CONTENT AND NEW REGULATION WILL DRIVE NEED FOR CYBERSECURITY STRATEGY IN AUTOMOTIVE VALUECHAIN



**Cybersecurity will become non-negotiable under the new UNECE WP.29 regulations to obtain vehicle type approval. This will affect 60 countries (~20M passenger vehicles)**

Source: Mckinsey – Cybersecurity in Automotive – March 2020

# GREEN ECS & DECARBONISATION

## CHALLENGES

### Quantification

Limited assessments on electronics components carbon footprint / non-harmonized method and disclosure

### End of life management

Products & used materials recyclability evaluation / limited recyclability rates of ECS

## RESEARCH NEEDS

### Quantification

Build a common shared database and carbon assessment methodology, integrating the role innovation on HW

### End of life management

Products & used materials recyclability - need for research projects

Decarbonisation is part of KDT priorities - first workshop organized (June 2021)

Proposal to develop shared use cases & methodology work in KDT upcoming calls

# ENABLE SHARED BENEFITS BETWEEN AUTOMOTIVE & ELECTRONICS VALUE CHAIN: PROPOSALS FOR COOPERATION

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## **Reinforce a shared understanding**

to cross exchange on HW, SW, architectures, systems optimization, etc.

## **Share the best talents**

Ramping up of recruitment and retention of talents, trained together in order to fit the needs of both sectors

## **Set up strategic partnerships**

Secure the capacities and shared roadmaps

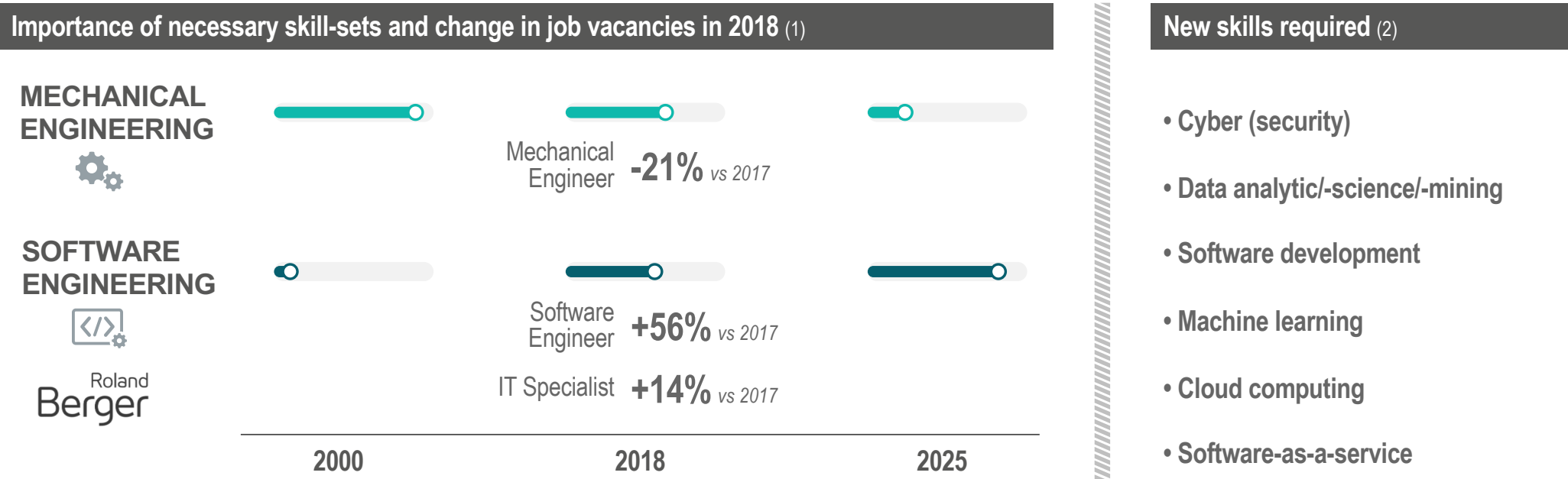
## **Build a regional approach**

Competition is tough, regional approaches will emerge, let's the EU electronics & automotive value chain work together

## **Sustainability**

Address the carbon reduction challenge of electronics

# FIND THE RIGHT TALENTS: THE REQUIRED SKILL-SET IS CHANGING



(3) According to Mckinsey, by 2030 there will be :

McKinsey

**250K** Software development jobs



**~30%** of these Software jobs in ADAS / AD and Infotainment

Source: (1) Roland Berger - Global Automotive Supplier Study 2019 (2) PWC - Digital Auto Report 2019 (3) Mckinsey - Automotive Software and Electronics 2030 - July 2019



SMART TECHNOLOGY  
FOR SMARTER MOBILITY